Abstracts

3-D Modeling of Interconnects in MMICs by the Method of Lines

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L. Vietzorreck and R. Pregla. "3-D Modeling of Interconnects in MMICs by the Method of Lines." 1996 MTT-S International Microwave Symposium Digest 96.1 (1996 Vol. I [MWSYM]): 347-350.

A new eigenmode algorithm, based on the method of lines, is presented for full-wave analysis of real 3-D structures. Finite conductor thickness, finite substrate and very short or long interconnection are rigorously modelled. S-parameters of air bridges, via holes and bead transitions investigated agree very well with literature.

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